Notice for TAIYO YUDEN Products

[For High Quality and/or Reliability Equipment (Automotive / Industrial Equipment)]

Please read this notice before using the TAIYO YUDEN products.

I REMINDERS

Product information in this catalog is as of October 2017. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

- Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available.
- Please conduct validation and verification of our products in actual condition of mounting and operating environment before using our products.
- The products listed in this catalog are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment), medical equipment classified as Class I or II by IMDRF, industrial equipment, and automotive interior applications, etc. Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment, medical equipment classified as Class III by IMDRF).

Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment*, medical equipment classified as Class IV by IMDRF, nuclear control equipment, undersea equipment, military equipment).

*Note: There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.

When our products are used even for high safety and/or reliability-required devices or circuits of general electronic equipment, it is strongly recommended to perform a thorough safety evaluation prior to use of our products and to install a protection circuit as necessary.

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

- Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.
- Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a fault or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.
- The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

CHIP BEAD INDUCTORS FOR POWER LINES (FB SERIES M TYPE)



STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY



Recommended Land Patterns	
Surface Mounting	
•Mounting and soldering conditions should be	÷
checked beforehand.	
c	
A B A A	

Туре	A	В	С
FB MJ1608	1.0	1.0	1.0
FB MJ2125	1.4	1.2	1.65
FB MJ3216	1.4	2.2	2.0
FB MJ4516	1.75	3.5	2.0
FB MH1608	1.0	1.0	1.0
FB MH2012	1.4	1.2	1.65
FB MH2016	1.4	1.2	2.0
FB MH3216	1.4	2.2	2.0
FB MH3225	1.4	2.2	2.9
FB MH4516	1.75	3.5	2.0
FB MH4525	1.75	3.5	2.9
			Unit : mm

Туре		w	т	е	Standard qu	uantity [pcs]
туре			· · · · · · · · · · · · · · · · · · ·	6	Paper tape	Embossed tape
FB MJ1608 (0603)	1.6 ± 0.2 (0.063 ± 0.008)	0.8 ± 0.2 (0.031 ± 0.008)	0.8 ± 0.2 (0.031 ± 0.008)	0.3 ± 0.2 (0.012 \pm 0.008)	4000	_
FB MJ2125	2.0±0.2	1.25±0.2	0.85±0.2	0.5±0.3	4000	_
(0805)	(0.079 ± 0.008)	(0.049 ± 0.008)	(0.033±0.008)	(0.020±0.012)	4000	
FB MJ3216 (1206)	3.2±0.3 (0.126±0.012)	1.6±0.2 (0.063±0.008)	1.1 ± 0.2 (0.043 ± 0.008)	0.5 ± 0.3 (0.020 ± 0.012)	-	2000
FB MJ4516 (1806)	4.5±0.3 (0.177±0.012)	1.6 ± 0.2 (0.063 ± 0.008)	1.1 ± 0.2 (0.043 ± 0.008)	0.5±0.3 (0.020±0.012)	-	2000
FB MH1608 (0603)	1.6±0.1 (0.063±0.004)	0.8±0.1 (0.031±0.004)	0.8±0.1 (0.031±0.004)	0.3±0.15 (0.012±0.006)	4000	-
FB MH2012 (0805)	2.0±0.2 (0.079±0.008)	1.25±0.2 (0.049±0.008)	0.85 ± 0.2 (0.033 ± 0.008)	0.5±0.3 (0.020±0.012)	4000	-
FB MH2016 (0806)	2.0±0.2 (0.079±0.008)	1.6±0.2 (0.063±0.008)	1.6 ± 0.2 (0.063 ± 0.008)	0.5±0.3 (0.020±0.012)	-	2000
FB MH3216 (1206)	3.2±0.3 (0.126±0.012)	1.6±0.2 (0.063±0.008)	1.6 ± 0.2 (0.063 ± 0.008)	0.5±0.3 (0.020±0.012)	-	2000
FB MH3225 (1210)	3.2±0.3 (0.126±0.012)	2.5±0.3 (0.098±0.012)	2.5±0.3 (0.098±0.012)	0.5±0.3 (0.020±0.012)	-	1000
FB MH4516 (1806)	4.5±0.3 (0.177±0.012)	1.6±0.2 (0.063±0.008)	1.6 ± 0.2 (0.063 ± 0.008)	0.5±0.3 (0.020±0.012)	-	2000
FB MH4525 (1810)	4.5±0.4 (0.177±0.016)	2.5±0.3 (0.098±0.012)	2.5±0.3 (0.098±0.012)	0.9 ± 0.6 (0.035 ± 0.024)	-	1000

• All the Multilayer Chip Bead Inductors of the catalog lineup are RoHS compliant.

Note)

- The exchange of individual specifications is necessary depending on the application and circuit condition. Please contact Taiyo Yuden sales channels.
- *1: Automotive (AEC-Q200 Qualified) products
 - < AEC-Q200 : AEC-Q200 qualified>

All the Multilayer Chip Bead Inductors of *1 marks are tested based on the test conditions and methods defined in AEC-Q200 by family item. Please consult with TAIYO YUDEN's official sales channel for the details of the product specification and AEC-Q200 test results, etc., and please review and approve TAIYO YUDEN's product specification before ordering.

• *2: Industrial products and Medical products

Standard type FB MJ1608

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MJ1608HS280NTV	28	±30%	100	0.007	4.0	0.8 ±0.2	*1, *2
FB MJ1608HM230NTV	23	±30%	100	0.007	4.0	0.8 ±0.2	*1, *2

FB MJ2125

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MJ2125HS250NTV	25	$\pm 30\%$	100	0.004	6.0	0.85 ± 0.2	*1, *2
FB MJ2125HS420-TV	42	±25%	100	0.008	4.0	0.85 ±0.2	*1, *2
FB MJ2125HM210NTV	21	±30%	100	0.004	6.0	0.85 ± 0.2	*1, *2
FB MJ2125HM330-TV	33	±25%	100	0.008	4.0	0.85 ±0.2	*1, *2
FB MJ2125HL8R0NTV	8	±30%	100	0.008	4.0	0.85 ± 0.2	*1, *2

FB MJ3216

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MJ3216HS480NTV	48	±30%	100	0.005	6.0	1.1 ±0.2	*1, *2
FB MJ3216HS800-TV	80	±25%	100	0.010	4.0	1.1 ± 0.2	*1, *2
FB MJ3216HM380NTV	38	±30%	100	0.005	6.0	1.1 ± 0.2	*1, *2
FB MJ3216HM600-TV	60	±25%	100	0.010	4.0	1.1 ±0.2	*1, *2
FB MJ3216HL160NTV	16	±30%	100	0.012	4.0	1.1 ±0.2	*1, *2

FB MJ4516

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MJ4516HS720NTV	72	$\pm 30\%$	100	0.007	6.0	1.1 ± 0.2	*1, *2
FB MJ4516HS111-TV	110	±25%	100	0.014	4.0	1.1 ±0.2	*1, *2
FB MJ4516HM560NTV	56	±30%	100	0.007	6.0	1.1 ± 0.2	*1, *2
FB MJ4516HM900-TV	90	±25%	100	0.014	4.0	1.1 ±0.2	*1, *2
FB MJ4516HL230NTV	23	±30%	100	0.014	3.5	1.1 ±0.2	*1, *2

${\sf High \ impedance \ type}({\sf GHz \ Band})$

FB	MH1608		

Part number	Nominal impedance Measuring frequency 100[MHz]		Nominal impedance Measuring frequency 1[GHz]		DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
	(Ω)	tolerance	(Ω)	tolerance	[32] (IIIax.)	[A] (IIIdx.)	[i i i i i i i i i i i i i i i i i i i	
FB MH1608HM470-TV	47	±25%	75	±40%	0.020	3.5	0.8 ±0.1	*1, *2
FB MH1608HM600-TV	60	±25%	100	±40%	0.025	3.0	0.8 ±0.1	*1, *2
FB MH1608HM101-TV	100	±25%	170	±40%	0.035	2.5	0.8 ±0.1	*1, *2
FB MH1608HM151-TV	150	±25%	270	±40%	0.050	2.1	0.8 ±0.1	*1, *2
FB MH1608HM221-TV	220	±25%	370	±40%	0.070	1.8	0.8 ±0.1	*1, *2
FB MH1608HM331-TV	330	±25%	520	±40%	0.130	1.2	0.8 ±0.1	*1, *2
FB MH1608HM471-TV	470	±25%	750	±40%	0.150	1.0	0.8 ±0.1	*1, *2
FB MH1608HM601-TV	600	±25%	900	±40%	0.170	0.9	0.8 ±0.1	*1, *2
FB MH1608HM102-TV	1000	±25%	1200	±40%	0.350	0.6	0.8 ±0.1	*1, *2
FB MH1608HL300-TV	30	±25%	120	±40%	0.028	2.6	0.8 ±0.1	*1, *2
FB MH1608HL600-TV	60	±25%	220	±40%	0.045	2.1	0.8 ±0.1	*1, *2
FB MH1608HL121-TV	120	±25%	540	±40%	0.130	1.2	0.8 ±0.1	*1, *2
FB MH1608HL221-TV	220	±25%	950	±40%	0.170	0.9	0.8 ±0.1	*1, *2
FB MH1608HL331-TV	330	±25%	1200	±40%	0.210	0.8	0.8 ±0.1	*1, *2
FB MH1608HL471-TV	470	±25%	1500	±40%	0.350	0.6	0.8 ±0.1	*1, *2
FB MH1608HL601-TV	600	±25%	1800	±40%	0.450	0.5	0.8 ±0.1	*1, *2

%)The rated current is the value of current at which the temperature of the element is increased by 40 deg.

High impedance type FB MH2012

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MH2012HM800-TV	80	±25%	100	0.025	2.7	0.85 ± 0.2	*1, *2
FB MH2012HM121-TV	120	±25%	100	0.032	2.5	0.85 ± 0.2	*1, *2
FB MH2012HM221-TV	220	±25%	100	0.060	2.0	0.85 ± 0.2	*1, *2
FB MH2012HM331-TV	330	±25%	100	0.080	1.8	0.85 ±0.2	*1, *2

FB MH2016

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MH2016HM121NTV	120	±30%	100	0.015	4.5	1.6 ±0.2	*1, *2
FB MH2016HM251NTV	250	±30%	100	0.050	2.0	1.6 ±0.2	*1, *2

FB MH3216

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MH3216HM221NTV	220	±30%	100	0.020	4.0	1.6 ±0.2	*1, *2
FB MH3216HM501NTV	500	±30%	100	0.070	2.0	1.6 ±0.2	*1, *2

FB MH3225

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MH3225HM601NTV	600	$\pm 30\%$	100	0.042	3.0	2.5 ± 0.3	*1, *2
FB MH3225HM102NTV	1000	±30%	100	0.100	2.0	2.5 ±0.3	*1, *2
FB MH3225HM202NTV	2000	$\pm 30\%$	100	0.130	1.2	2.5 ± 0.3	*1, *2

FB MH4516

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MH4516HM851NTV	850	$\pm 30\%$	100	0.100	1.5	1.6 ±0.2	*1, *2

FB MH4525

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MH4525HM102NTV	1000	±30%	100	0.060	3.0	2.5 ±0.3	*1, *2
FB MH4525HM162NTV	1600	±30%	100	0.130	2.0	2.5 ± 0.3	*1, *2

High current type

Part number	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]	Note
FB MJ1608HS220NTW	22	±30%	100	0.004	7.5	0.8 ±0.2	*1, *2
FB MJ1608HS280NTW	28	±30%	100	0.006	6.0	0.8 ±0.2	*1, *2
FB MJ1608HM180NTW	18	±30%	100	0.004	7.5	0.8 ±0.2	*1, *2
FB MJ1608HM230NTW	23	±30%	100	0.006	6.0	0.8 ±0.2	*1, *2

%) The rated current is the value of current at which the temperature of the element is increased by 40 deg.

ELECTRICAL CHARACTERISTICS

for High Quality Equipment





for High Quality Equipment





Derating of Rated Current

FB series M type

Derating of current is necessary for FB series M type depending on ambient temperature. Please refer to the chart shown below for appropriate derating of current.



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/). NOISE SUPPRESSION COMPONENTS / FERRITE BEAD INDUCTORS

CHIP BEAD INDUCTORS FOR POWER LINES (FB SERIES M TYPE)

PACKAGING

①Minimum Quantity				
Turne	Standard Quantity[pcs]			
Туре	Paper Tape	Embossed Tape		
1608(0603)	4000	-		
2125(0805)	4000	-		
2012(0805)	4000	-		
2016(0806)	—	2000		
3216(1206)	—	2000		
3225(1210)	—	1000		
4516(1806)	—	2000		
4525(1810)	_	1000		
4532(1812)	_	2000		

(2) Tape Material





③Taping Dimensions

Paper tape (0.315 inches wide)





Tumo	Chip	Cavity	Insertion Pitch	Tape Thickness
Туре	A	В	F	Т
FBMJ1608 FBMH1608 (0603)	1.0 ± 0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)
FBMJ2125 FBMH2012 (0805)	1.5 ± 0.2 (0.059 ± 0.008)	2.3±0.2 (0.091±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)

Unit : mm(inch)

Embossed tape (0.315 inches wide)



Туре	Chip	Cavity	Insertion Pitch	Tape Thickness	
туре	А	В	F	К	Т
FBMH2016	1.8±0.2	2.2±0.2	4.0±0.2	2.6max	0.6max
(0806)	(0.071 ± 0.008)	(0.087±0.008)	(0.157 ± 0.008)	(0.102max)	(0.024max)
FBMJ3216	1.9±0.2	3.5±0.2	4.0±0.2	1.5max	0.3max
(1206)	(0.075 ± 0.008)	(0.138 ± 0.008)	(0.157 ± 0.008)	(0.059max)	(0.012max)
FBMH3216	1.9±0.2	3.5±0.2	4.0±0.2	2.6max	0.6max
(1206)	(0.075 ± 0.008)	(0.138 ± 0.008)	(0.157 ± 0.008)	(0.102max)	(0.024max)
FBMH3225	2.8±0.2	3.5±0.2	4.0±0.2	4.0max	0.6max
(1210)	(0.110 ± 0.008)	(0.138±0.008)	(0.157 ± 0.008)	(0.157max)	(0.024max)

Unit : mm(inch)

Embossed tape (0.472 inches wide)



T	Chip	Chip Cavity		Tape Thickness	
Туре	Α	В	F	К	Т
FBMJ4516	1.9±0.2	4.9 ± 0.2	4.0±0.2	1.5max	0.3max
(1806)	(0.075 ± 0.008)	(0.193 ± 0.008)	(0.157 ± 0.008)	(0.059max)	(0.012max)
FBMH4516	1.9±0.2	4.9±0.2	4.0±0.2	2.6max	0.6max
(1806)	(0.075 ± 0.008)	(0.193 ± 0.008)	(0.157 ± 0.008)	(0.102max)	(0.024max)
FBMH4525	2.9±0.2	4.9±0.2	4.0±0.2	4.0max	0.6max
(1810)	(0.114±0.008)	(0.193 ± 0.008)	(0.157 ± 0.008)	(0.157max)	(0.024max)
FBMH4532	3.6±0.2	4.9±0.2	8.0±0.2	4.0max	0.6max
(1812)	(0.142 ± 0.008)	(0.193±0.008)	(0.315 ± 0.008)	(0.157max)	(0.024max)
	•	•			Unit · mm (inc

Unit : mm(inch)



4Leader and Blank portion



Direction of tape feed

Insertion leader is 400 mm or more (including 20 empty cavities) Empty cavities at end of reel: 40 holes or more

⑤Reel size



Туре	φD	Ød	W	t
FBMJ1608			10.0 ± 1.5	
FBMJ2125			(0.394 ± 0.059)	
FBMJ3216			(0.394 ± 0.039)	
FBMJ4516			14.0 ± 1.5 (0.551 ± 0.059)	
FBMH1608	180+0/-3	60+1/-0		2.5max
FBMH2012	(7.09+0/-0.118)	$(2.36 \pm 0.039 / -0)$	10.0 ± 1.5	(0.098max)
FBMH2016			(0.394 ± 0.059)	
FBMH3216	6		(0.394 ± 0.059)	
FBMH3225				
FBMH4516	7		14.0±1.5	
FBMH4525			(0.551 ± 0.059)	
FBMH4532	330±2.0	100±1.0	14.0±2.0	3.0max
FBMH4332	(12.99 ± 0.080)	(3.94 ± 0.039)	(0.551 ± 0.080)	(1.181max)
				Unit : mm(inch)

6Top tape strength



Base tape The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.

CHIP BEAD INDUCTORS FOR POWER LINE (FB SERIES M TYPE)

RELIABILITY DATA

1. Operating Temperature Range			
Specified Value	$-40^{\circ}C \sim +125^{\circ}C$ (Including self-generated heat)		
Test Methods and Remarks	Including self-generated heat		

2. Storage Tempera	2. Storage Temperature Range			
Specified Value	$-40^{\circ}C \sim +85^{\circ}C$			
Test Methods and Remarks	*Note: -5 to $+40^{\circ}$ C in taped packaging			

3. Impedance				
Specified Value	Within the specified tolera	ithin the specified tolerance		
Test Methods and Remarks	Measuring equipment Measuring frequency	: Impedance analyzer (HP4291A) or its equivalent : 100±1 MHz		

4. DC Resistance	
Specified Value	Within the specified range
Test Methods and	Four-terminal method
Remarks	Measuring equipment : Milliohm High-Tester 3226 (Hioki Denki) or its equivalent

5. Rated Current	
Specified Value	Within the specified range

6. Vibration	6. Vibration		
Specified Value	Appearance	: No significant abnormality	
	Impedance change	: Within $\pm 30\%$ of the initial value	
	According to JIS C 004	0.	
	Vibration type	: A	
Test Methods and	Time	: 2 hrs each in X,Y, and Z directions Total: 6 hrs	
Remarks	Frequency range	: 10 to 55 to 10Hz (/min.)	
	Amplitude	: 1.5 mm (shall not exceed acceleration 196m/s²)	
	Mounting method	: Soldering onto PC board	

7. Solderability			
Specified Value	90% or more of immersed surface of terminal electrode shall be covered with fresh solder.		
Test Methods and	Solder temperature Immersion time	: 230±5°C : 4±1 sec.	
Remarks	Preconditioning Immersion and Removal speed	: Immersion into flux. : 25mm/sec.	

Specified Value		icant abnormality 30% of the initial value
	Preheating Resistance to Soldering Heat	: 150℃ for 3 min. : 260±5℃
Test Methods and	Duration	: 10±0.5 sec.
Remarks	Preconditioning	: Immersion into flux.
	Immersion and Removal speed	: 25mm/sec.
	Recovery	: 2 to 3 hrs of recovery under the standard condition after the test.

Thermal Shock				
pecified Value	Appearar Impedanc		nt abnormality ⁄ —10% of the initial value	
		g to JIS C 0025. ns for 1 cycle		_
	Step	Temperature (°C)	Duration (min.)	
	1	-40±3°C	30 ± 3	
t Methods and	2	Room Temperature	Within 3	
	3	85±2°C	30 ± 3	
Remarks	4	Room Temperature	Within 3	
	Number of Mounting Recovery	method : Soldering or		d condition after the removal from test chamber.

10. Resistance to H	10. Resistance to Humidity (steady state)		
Specified Value	Appearances Impedance change	: No significant abnormality : Within $\pm 30\%$ of the initial value	
Test Methods and Remarks	Temperature Humidity Duration Mounting method Recovery	: 40±2°C : 90 to 95% RH : 500+24/-0 : Soldering onto PC board : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.	

11. Loading under D	11. Loading under Damp Heat		
Specified Value	Appearance Impedance change	No ignificant abnormality Within $\pm 30\%$ of the initial value	
Test Methods and Remarks	Temperature Humidity Applied current Duration Mounting method Recovery	: 40±2°C : 90 to 95%RH : Rated current : 500+24/-0 hrs : Soldering onto PC board : 2 to 3hrs of recovery under the standard condition after the removal from test chamber.	

12. High Temperatu	12. High Temperature Loading Test		
Specified Value	Appearance Impedance change	: No significant abnormality : Within $\pm 30\%$ of the initial value	
Test Methods and Remarks	Temperature Duration Applied current Mounting method Recovery	: 85±2°C : 500+24/-0 hrs : Rated current : Soldering onto PC board : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.	

13. Bending Strength		
Specified Value	Appearance : No mechanical damage.	
Test Methods and Remarks	Warp : 2mm Testing board : Glass epoxy-resin substrate Thickness : 0.8mm Board R-230 Warp 45±2 45±2 (Unit: mm)	



Note on standard condition: "standard condition" referred to herein is defined as follows:

5 to 35 $^{\circ}\text{C}\,$ of temperature, 45 to 85% relative humidity and 86 to 106kPa of air pressure.

When there are questions concerning measurement results:

In order to provide correlation data, the test shall be conducted under condition of $20\pm 2^{\circ}$ C of temperature, 60 to 70% relative humidity and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition."



PRECAUTIONS

1. Circuit Design	
Precautions	 Operating environment The products listed in this catalogue are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment), general medical equipment, industrial equipment, and automotive interior applications, etc. Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., specially controlled medical equipment, transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment). Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment, nuclear control equipment, undersea equipment, military equipment, etc.). Rated current Rated current of this product is shown in this catalogue, but please be sure to have the base board designed with adequate inspection in case of the generation of heat becomes high within the rated current range when the base board is in high resistance or in bad heating conditions.

2. PCB Design	
Precautions	 Land pattern design 1. Please refer to a recommended land pattern.
3. Consideration	s for automatic placement
Precautions	 Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand.

Technical	◆Adjustment of mounting machine
considerations	1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering	
Precautions	 Wave soldering Please refer to the specifications in the catalog for a wave soldering. Reflow soldering Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. Lead free soldering When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, etc. sufficiently. Preheating when soldering the temperature difference between soldering and remaining heat should not be greater than 150°C. Cooling : The temperature difference between the components and cleaning process should not be greater than 100°C. Recommended conditions for using a soldering iron Put the soldering iron on the land-pattern. Soldering iron's temperature – Below 350°C Duration – 3 seconds or less The soldering iron should not directly touch the inductor.
Technical considerations	 Wave, Reflow, Lead free soldering If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. [Recommended reflow condition]

> This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification.

For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

	◆ Handling
	1. Keep the inductors away from all magnets and magnetic objects.
	♦Setting PC boards
	1. When setting a chip mounted base board, please make sure that there is no residual stress to the chip by distortion in the board or at screw part.
Precautions	◆Breakaway PC boards (splitting along perforations)
	1. When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board.
	2. Board separation should not be done manually, but by using the appropriate devices.
	♦Mechanical considerations
	1. Please do not give the inductors any excessive mechanical shocks.
	◆ Handling
	1. There is a case that a characteristic varies with magnetic influence.
	♦Setting PC boards
Technical	1. There is a case that a characteristic varies with residual stress.
considerations	◆Breakaway PC boards (splitting along perforations)
	1. Planning pattern configurations and the position of products should be carefully performed to minimize stress.
	♦ Mechanical considerations
	1. There is a case to be damaged by a mechanical shock.

b. Storage conditions	
Precautions	 Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. Recommended conditions Ambient temperature -5~40°C Humidity Below 70% RH The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, inductors should be used within 6 months from the time of delivery.
Technical considerations	 Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.